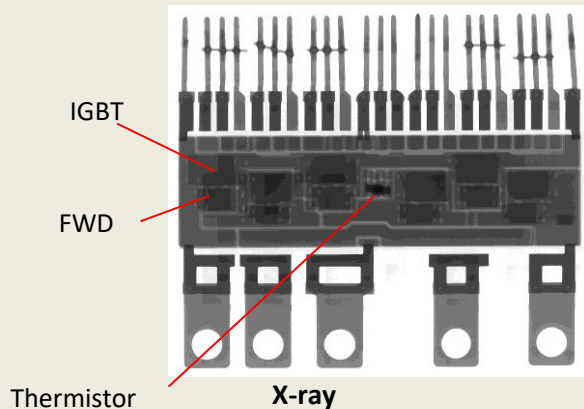


INFINEONS POWER MODULE STRUCTURE ANALYSIS REPORT

February 2020. LTEC Corporation released a detailed structure analysis reports of the Infineon power module used in the Hyundai automotive IONIQ PHEV.



Module



Thermistor

X-ray

Product overview

IGBT power module with double-sided cooling structure, components embedded in the PCB, and Direct Bonded Copper (DBC) at the top and bottom layers of the PCB to enhance heat removal.

Report content

The 84-page report includes:

- Structural details: Module appearance, X-ray observations.
- Layer-by-layer analysis including partial circuit schematic, terminal connection method, and other details of interest related to manufacturing technology.
- Module cross section analysis: SEM-EDX analysis, resin component analysis by Fourier transform infra-red spectroscopy analysis (FT-IR).
- Die cross-sectional analysis (transistor and die edge): Semiconductor layers, circuit schematic, and die layout confirmation.

Note: The report price may change over time. For current price contact info@ltecusa.com.

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Table of Contents

Structure Analysis Report

	Page
<u>Device summary</u>	
Table 1, Executive Summary	3
<u>Analysis results summary</u>	
Table 2. Device structure (Si IGBT)	5
Table 3. Material	6
Table 4. Module structure	7
<u>Module analysis</u>	
Overview	9
Layer-by-layer analysis	12
Cross sections	28
<u>IGBT die analysis</u>	
Plane view (optical microscope)	42
Plane view, Scanning Electron Microscope (SEM)	60
Cross-sectional structure analysis (SEM)	65
<u>Mold resin</u>	
Material analysis	83



Excerpts of figures and tables

(English text is provided in the report)

